

# Detector Design Principles

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## Ionization (charge separation) Detectors

- Ionization chambers (solid-state and gas)
- Proportional counters
- Avalanche counters
- Geiger-Müller counters
- Cloud/bubble chambers
- Track detectors

## Scintillation Detectors

- Phosphorescence counters
- Fluorescence counters (inorganic solid crystal scintillators, organic solid and liquid scintillators)
- Čerenkov counters

## Associated Techniques

- Photo sensors and multipliers
- Charged-coupled devices
- Electronic pulse shape analysis
- Processing/acquisition electronics

Detection Of  
Ionizing Radiation  
**Solid-State Ionization  
Chambers**



# Ionization Chambers (Solid-State and Gas Medium)

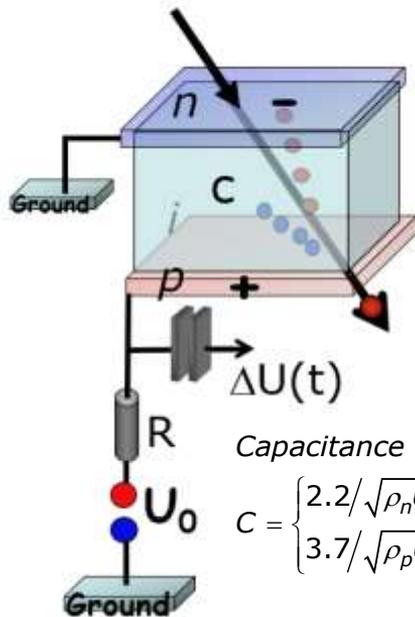
**General principle:** Radiation dissipates energy  $E$  via production of electron-ion ( $e^-$ ,  $h^+$ ) pairs in a medium enclosed between electrodes (Anode, Cathode). Electronic  $E$  signal picked up at A or C.

Gas volume between capacitor C electrodes.

Energy  $E \rightarrow N_{\text{ion pairs}} = E/\varepsilon_{\text{ip}}(\text{gas})$

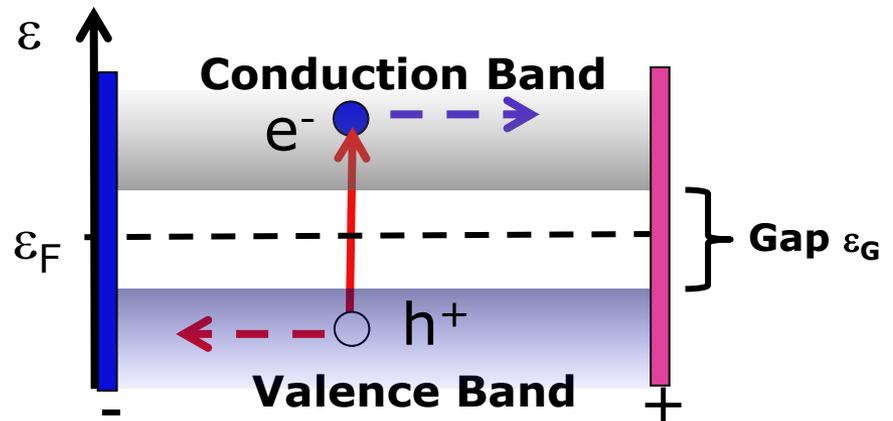
Semiconductor  $n$ -,  $p$ -,  $i$ -types  $Si$ ,  $Ge$ ,  $GaAs$ ,...

Band structure of solids VB gap CB.



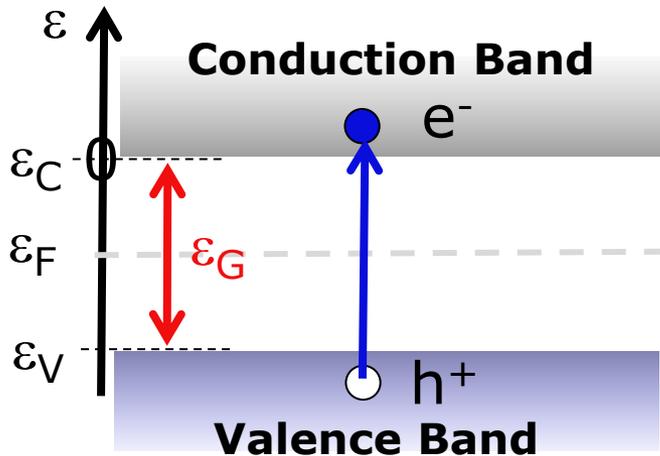
Capacitance  $Si$  :

$$C = \begin{cases} 2.2/\sqrt{\rho_n U_0} \text{ pF/mm}^2 \\ 3.7/\sqrt{\rho_p U_0} \text{ pF/mm}^2 \end{cases}$$



Ionization lifts  $e^-$  up to CB, leaves hole  $h^+$  in VB  $\rightarrow$  free charge carriers, produce  $\Delta U(t) \sim E$ .

# Particles and Holes in **Pure** Semi-Conductors



$$e^- : f_e(\varepsilon) = \left[ 1 + \exp\left(\frac{\varepsilon + \varepsilon_G/2}{kT}\right) \right]^{-1}$$

$$h^+ : f_h(\varepsilon) = \left[ 1 + \exp\left(\frac{-\varepsilon + \varepsilon_G/2}{kT}\right) \right]^{-1}$$

Small gaps  $\varepsilon_G$  (Ge)  $\rightarrow$   
high thermal currents.  
Reduce by cooling.

Fermi gas of electrons (and holes)  
Fermion statistics @ temperature  $T$ :

$n_e, n_h = \#$  of occupied  $e^-$  or  $h^+$  states  
 $f_e, f_h \leq 1$  occupation numbers

$$n_e(\varepsilon) = \frac{(2m)^{2/3} V}{2\pi^2 \hbar^3} \sqrt{\varepsilon} \cdot f_e(\varepsilon) \quad V = \text{volume}$$

$$n_h(\varepsilon) = \frac{(2m)^{2/3} V}{2\pi^2 \hbar^3} \sqrt{|\varepsilon|} \cdot f_h(\varepsilon) \quad n_e = n_h !!$$

$$\varepsilon_F = \varepsilon_C - \varepsilon_G/2 = -\varepsilon_G/2 \quad \text{for } \varepsilon_C := 0$$

$$f_e(\varepsilon) = \left[ 1 + \exp\left(\frac{\varepsilon - \varepsilon_F}{kT}\right) \right]^{-1}$$

$$\xrightarrow{kT \approx 25 \text{ meV} \ll \varepsilon_G} \exp\left(-\frac{\varepsilon + \varepsilon_G/2}{kT}\right)$$

$$\langle n_e^2 \rangle = \langle n_e n_h \rangle = \left( \frac{(2m)^{2/3} V}{2\pi^2 \hbar^3} \right)^2 \langle \varepsilon \rangle \exp\left(-\frac{\varepsilon_G}{kT}\right)$$

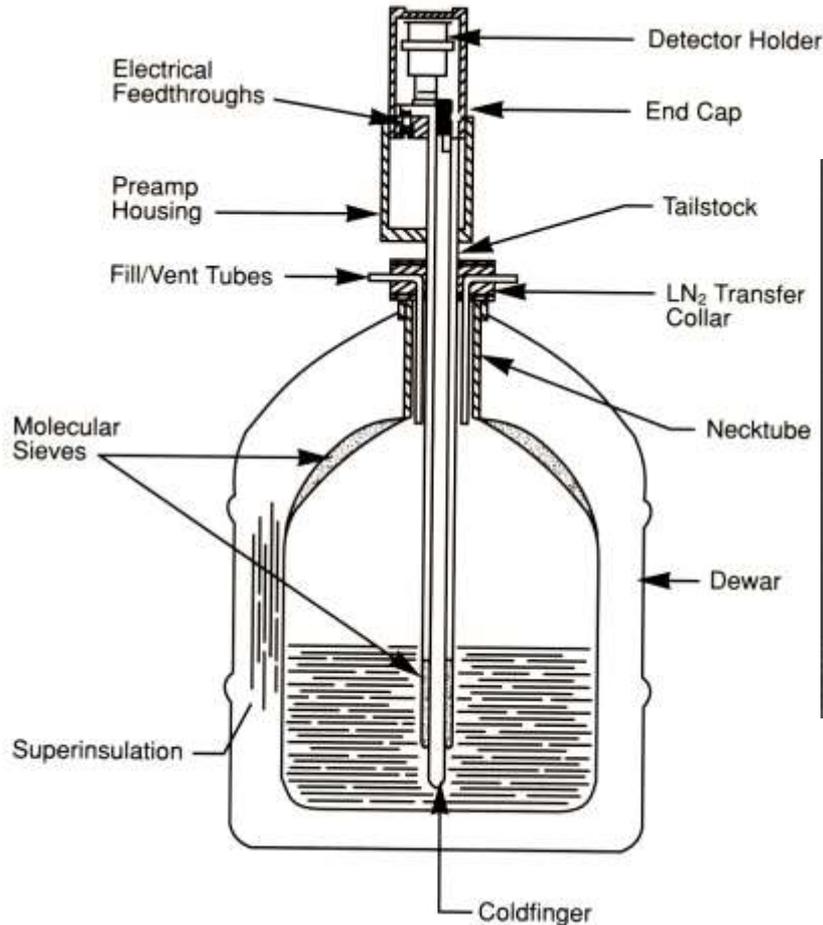
$$\langle n_e \rangle_{rms} \sim \exp\left(-\frac{\varepsilon_G}{2kT}\right)$$

$\propto$  noise generating  
conductivity at  $T$

# Hyper-Pure Germanium (HpGe) $\gamma$ -ray Detectors

Hyper-pure Ge detectors for  $\gamma$ -rays: High  $\sigma_{\text{photo}}$ , small gap  $\rightarrow$  high efficiency & high resolution. Cool to  $-77^\circ\text{C}$  ( $\text{LN}_2$ ) because of small gap  $E_G$ .

## Ge Cryostat (Canberra)

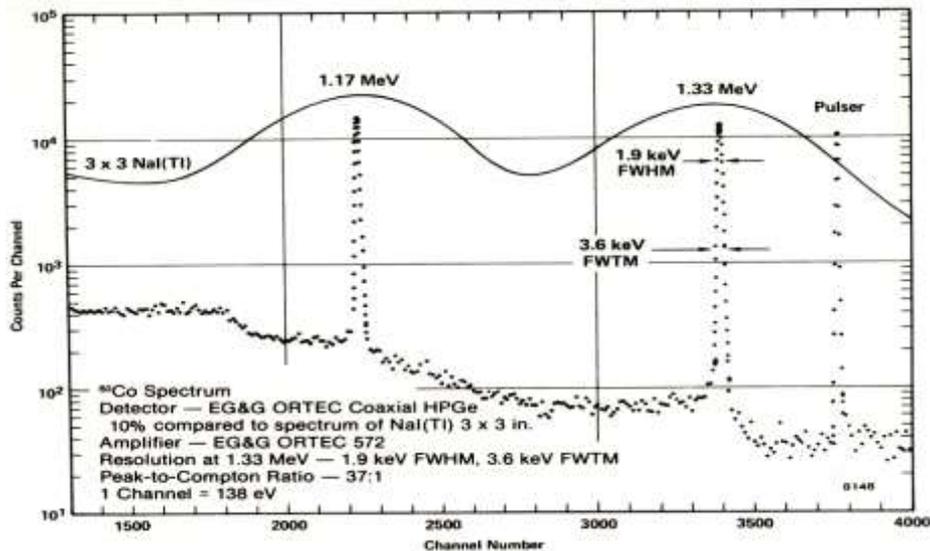


## Ge cryostat geometries (Canberra)



Type used in large numbers in NP arrays with anti-Compton shield detectors.

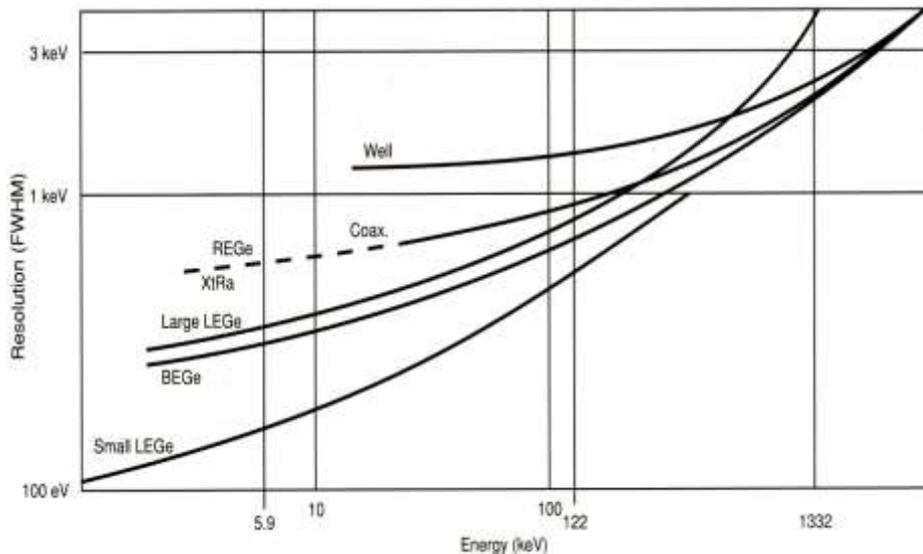
# Properties of Ge Detectors: Energy Resolution



Superior energy resolution, compared to NaI

$$\Delta E_{\gamma} \sim 0.5 \text{ keV} @ E_{\gamma} = 100 \text{ keV}$$

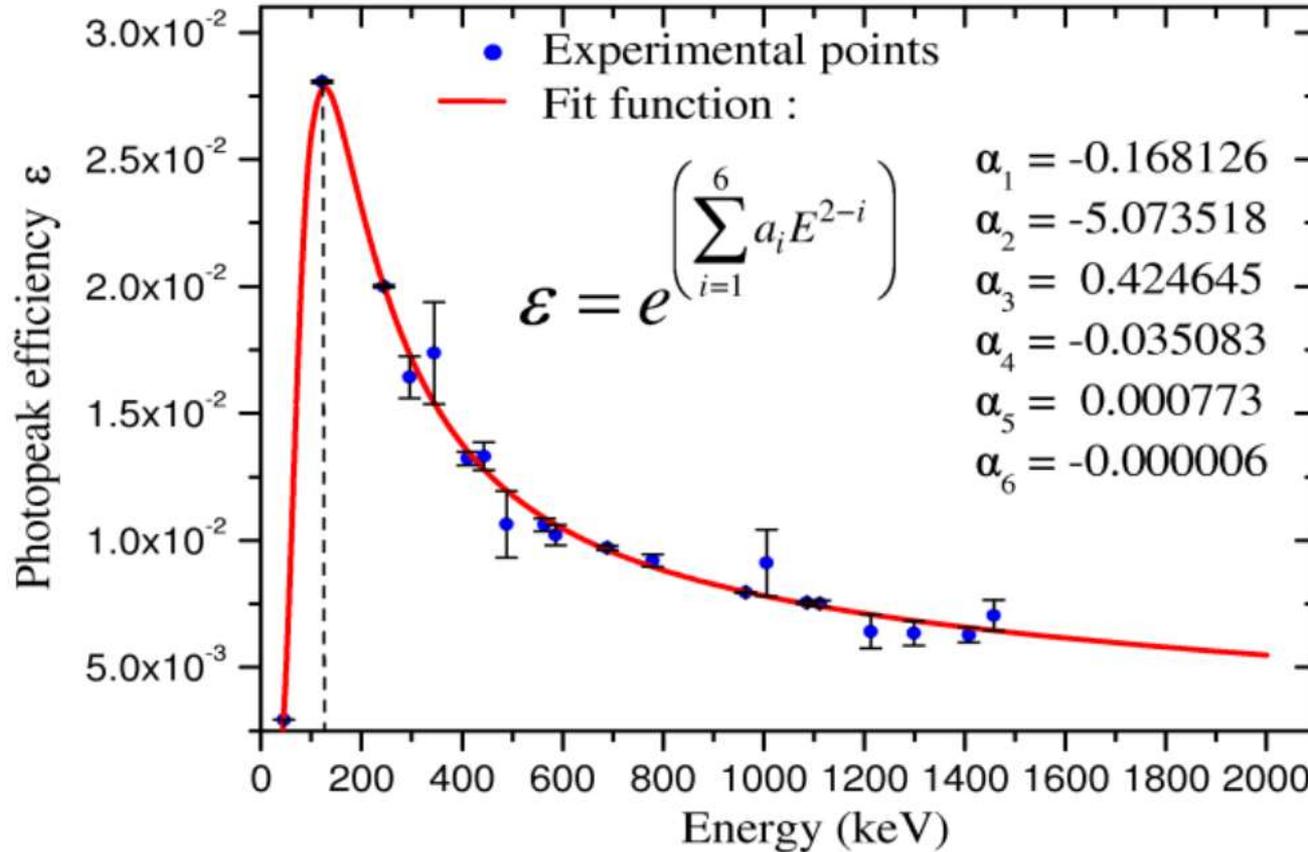
Higher peak/Compton ratios



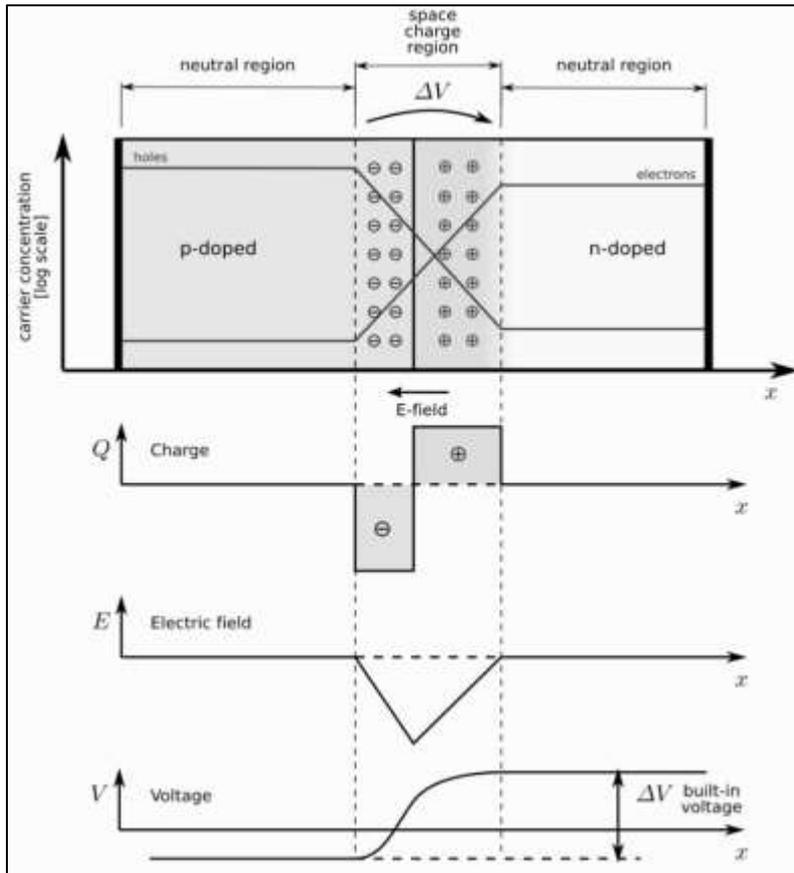
Size=dependent small detection efficiencies of Ge detectors  $\epsilon \sim 10\% \rightarrow$  solution: bundle in  $4\pi$ -arrays *GammaSphere, Greta EuroGam, Tessa, ...*

# Typical Energy Resolution of a HPGe Detector

Detector GEM P30185



# Semiconductor Junctions and Barriers



Need detector for rad-induced charges  
 → otherwise, no free carriers allowed.

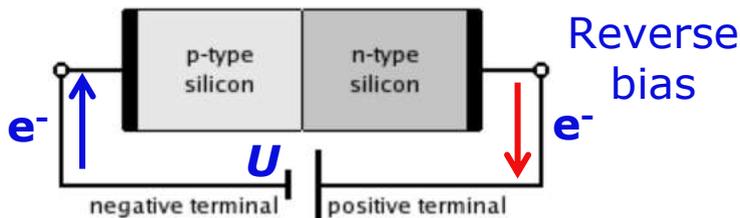
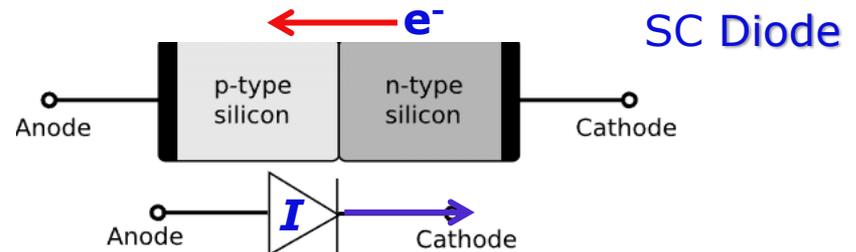
Difficult to make: perfect *i*-type (intrinsic) Si = chemical Group IV.

**Trick:** Deplete part of combination (SC junction)

*n*-type Si: by doping with *Li* or Group V  $e^-$  donor atoms (*P, Sb, As*),  
*p*-type Si: by doping with Group III  $e^-$  acceptor atoms (*B, Al, ...*).

Junctions diffuse donors and acceptors into Si bloc from different ends.

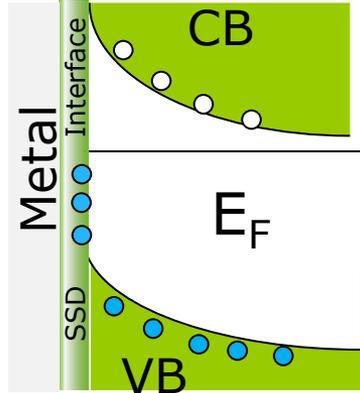
Diffusion at interface →  $e^-/h^+$  annihilation → space charge=zone depleted of carriers



Electrons move easily through the junction *from n to p* but *not from p to n*, and the reverse is true for holes.

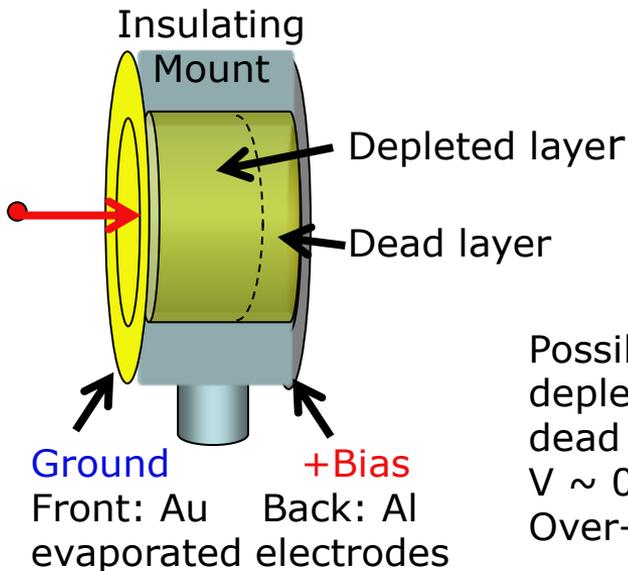
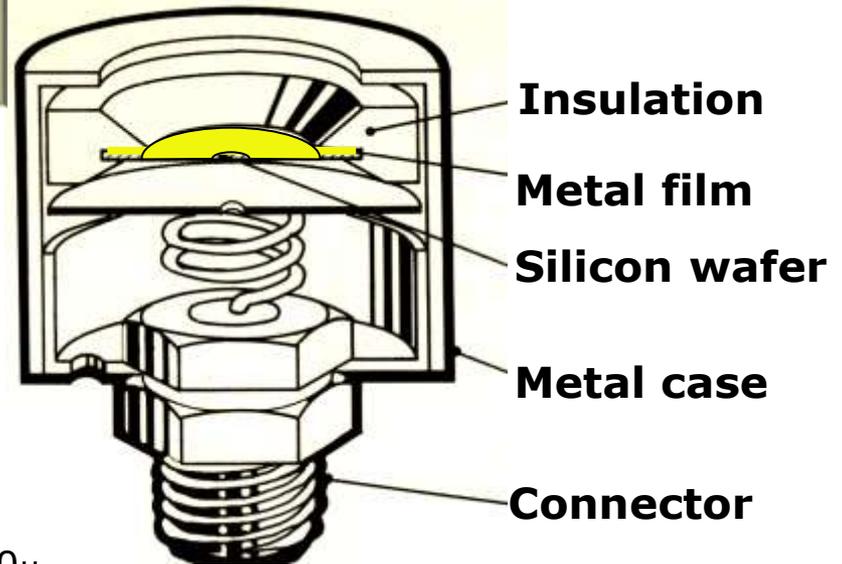
# Surface Barrier Detectors

## Semiconductor/ Metal Junction



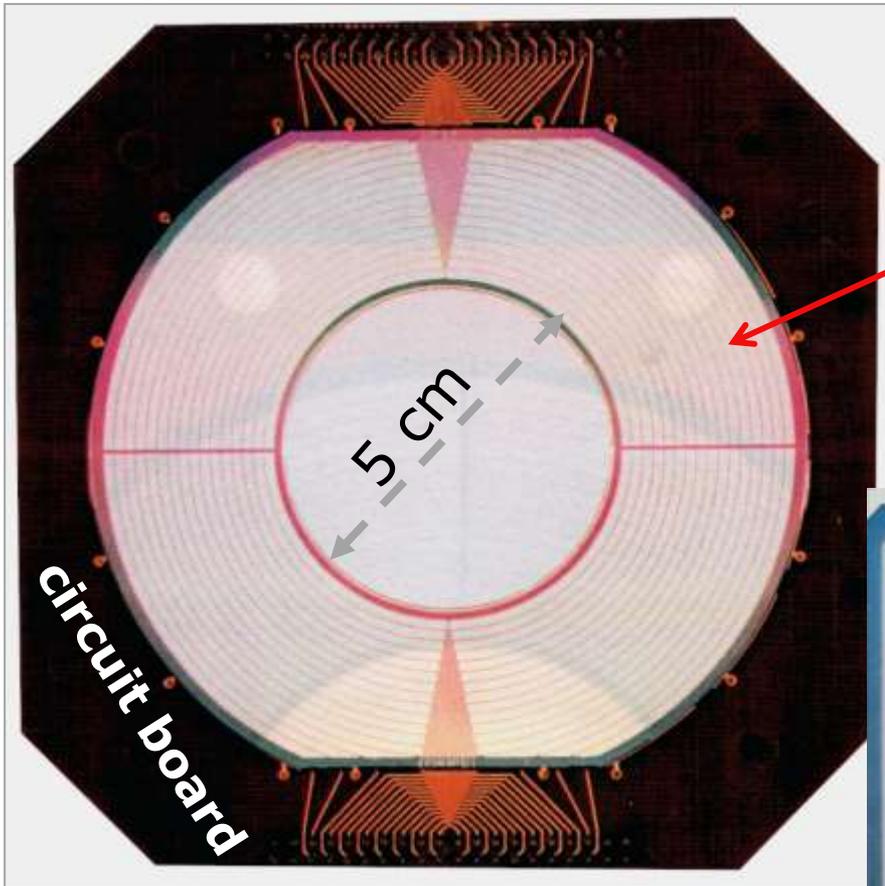
Thin metal film on Si surface produces space charge (SSD surface states) = effective barrier (contact potential) → depleted zone with no free charges. Apply reverse bias to increase depletion depth. Free charge carriers created from incident radiation →  $\Delta V$  signal

ORTEC  
HI detector



Possible: electrical  
depletion depth  $\sim 100\mu$   
dead layer  $d_d \leq 1\mu$   
 $V \sim 0.5V/\mu$   
Over-bias reduces  $d_d$

# Si-Strip Detectors



Typically  $(300-500)\mu$  thick.  
Fully depleted, thin dead layer.

Annular:

16 bins ("strips") in polar ( $\theta$ ),  
4 in azimuth ( $\phi$ ) (Micron Ltd.)

Rectangular with 7 strips

